

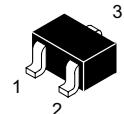
WPM3407

Single P-Channel, -30 V, -4.4A,Power MOSFET

Description

The WPM3407 uses advanced trench technology to provide excellent $R_{DS(on)}$ with low gate charge. This device is suitable for use in DC-DC conversion applications. Standard Product WPM3407 is Pb-free.

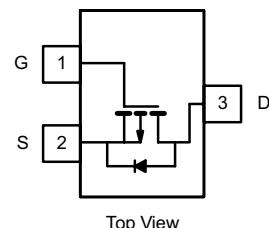
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SOT 23-3

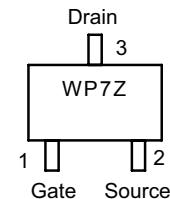
pin connections :

P-Channel



Top View

Marking:



WP7= Specific Device Code
Z = Date Code

ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ\text{C}$, unless otherwise noted					
Parameter		Symbol	10 S	Steady State	Unit
Drain-Source Voltage		V_{DS}	-30		V
Gate-Source Voltage		V_{GS}	± 20		
Continuous Drain Current ($T_J = 150^\circ\text{C}$) ^a	$T_A = 25^\circ\text{C}$	I_D	-4.4	-3.7	A
	$T_A = 70^\circ\text{C}$		-3.5	-2.9	
Pulsed Drain Current		I_{DM}	-20		
Maximum Power Dissipation ^a	$T_A = 25^\circ\text{C}$	P_D	1.4	1.0	W
	$T_A = 70^\circ\text{C}$		0.9	0.6	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 150		°C

Order information

Part Number	Package	Shipping
WPM3407-3/TR	SOT23-3	3000Tape&Reel

THERMAL RESISTANCE RATINGS

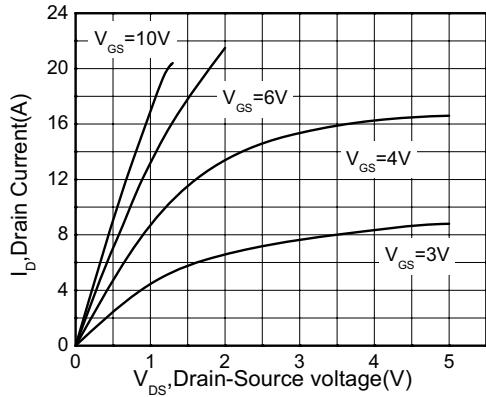
Parameter	Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance ^a	$R_{\theta JA}$	70	90	°C/W
Steady State		90	125	
Junction-to-Case Thermal Resistance	Steady State	$R_{\theta JC}$	50	80

a. Surface Mounted on FR4 Board using 1 in sq pad size, 1oz Cu.

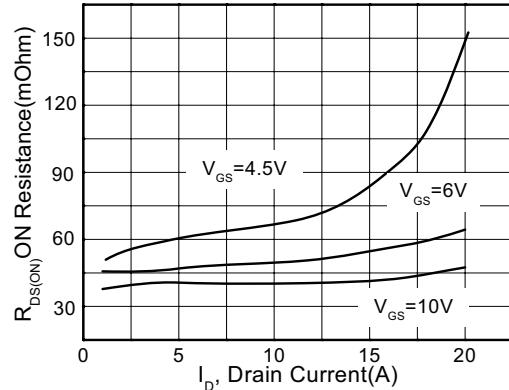
Electrical Characteristics ($T_J = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static Parameters						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0 V, I_D = -250 \mu A$	-30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 2.4 V, V_{GS} = 0 V$	$T_J = 25^\circ C$		-1	μA
			$T_J = 85^\circ C$		-10	
Gate-Source Leakage Current	I_{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS} = V_{DS}, I_D = -250 \mu A$	-1.0	-2.0	-3.0	V
Drain-source On-Resistance	$R_{DS(on)}$	$V_{GS} = -10 V, I_D = -4.4 A$		36	46	$m\Omega$
		$V_{GS} = -4.5, I_D = -3.0 A$		53	66	
Forward Recovery Voltage	V_{SD}	$V_{GS} = 0 V, I_S = -1.0 A$	-0.5	-0.79	-1.5	V
Forward Transconductance	g_{FS}	$V_{DS} = -5.0 V, I_D = -5 A$	5	8		S
Dynamic						
Input Capacitance	C_{iss}	$V_{GS} = 0 V, f = 1.0 MHz, V_{DS} = -15 V$	700	950	1200	pF
Output Capacitance	C_{oss}		90	120	150	
Reverse Transfer Capacitance	C_{rss}		75	100	125	
Total Gate Charge	$Q_{g(tot)}$	$V_{GS} = -10 V, V_{DS} = -15 V, I_D = -5 A$	13	18	23	nC
Threshold Gate Charge	$Q_{g(th)}$		1.5	2	2.5	
Gate- Source Charge	Q_{gs}		2	2.5	3	
Gate- Drain Charge	Q_{gd}		3	3.8	4.5	
Gate Resistance	R_g	$V_{GS} = 0 V, V_{DS} = 0 V, f = 1.0 MHz$		5	8	Ω
Switching Parameters						
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = -10 V, V_{DS} = -15 V, I_D = -4.3 A, R_G = 6 \Omega$	8	11	15	ns
Rise Time	t_r		4	6	9	
Turn-Off Delay Time	$t_{d(off)}$		30	40	50	
Fall Time	t_f		5	7.5	10	
Body Diode Reverse Recovery Time	t_{rr}	$I_F = -5 A, dI/dt = 100 A/\mu s$		25		ns
Body Diode Reverse Recovery Charge	Q_{rr}	$I_F = -5 A, dI/dt = 100 A/\mu s$		14		nC

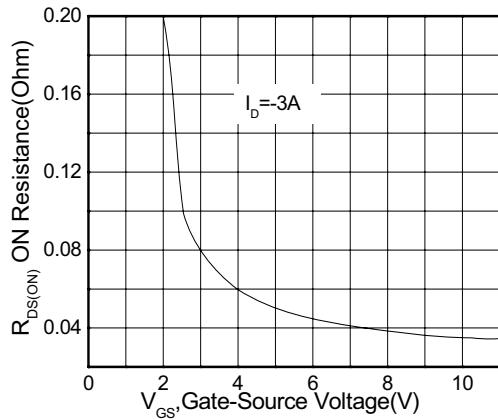
Typical Performance Characteristics



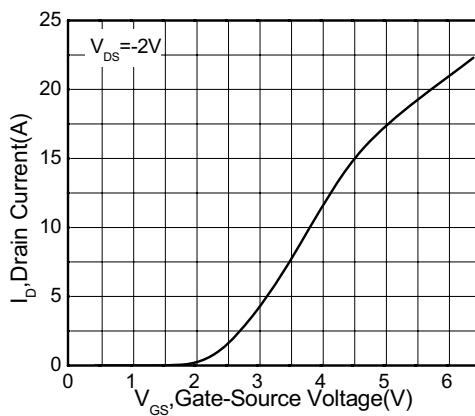
Drain Current VS Drain-Source voltage



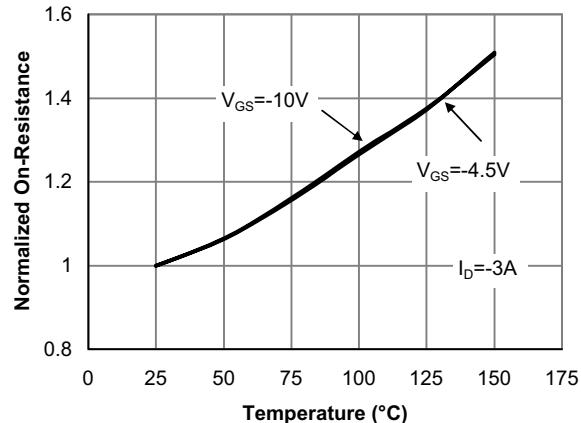
Drain Current vs ON Resistance



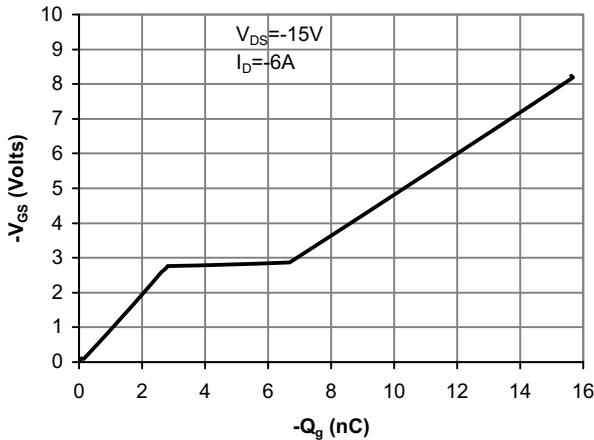
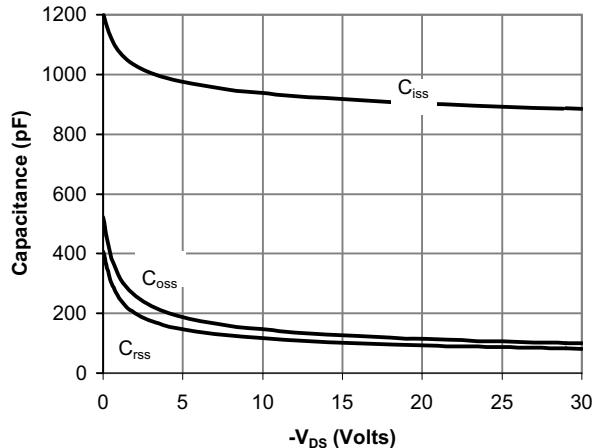
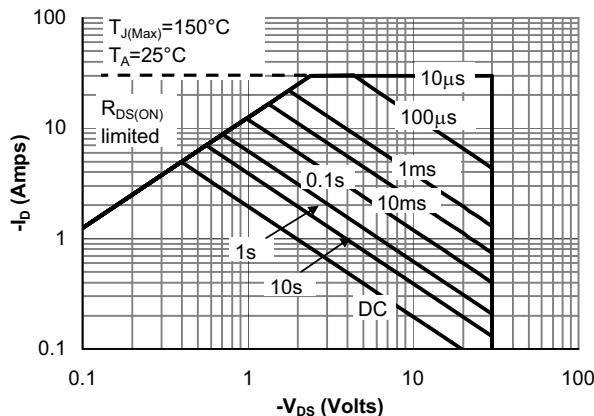
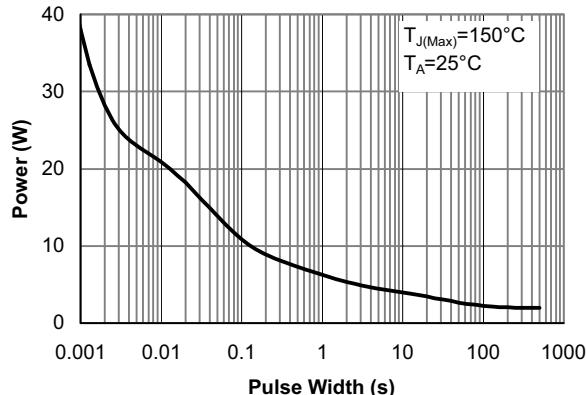
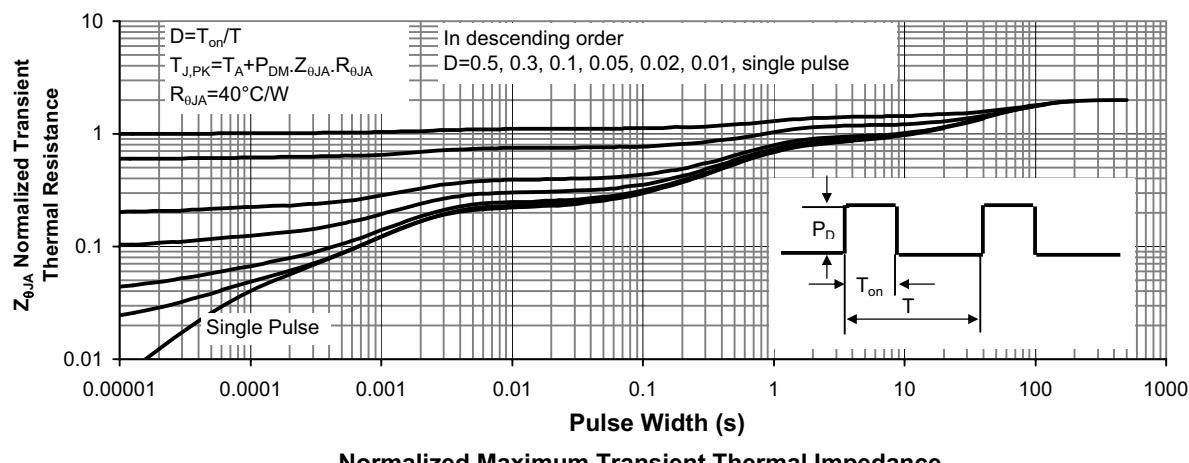
Gate-Source Voltage vs ON Resistance



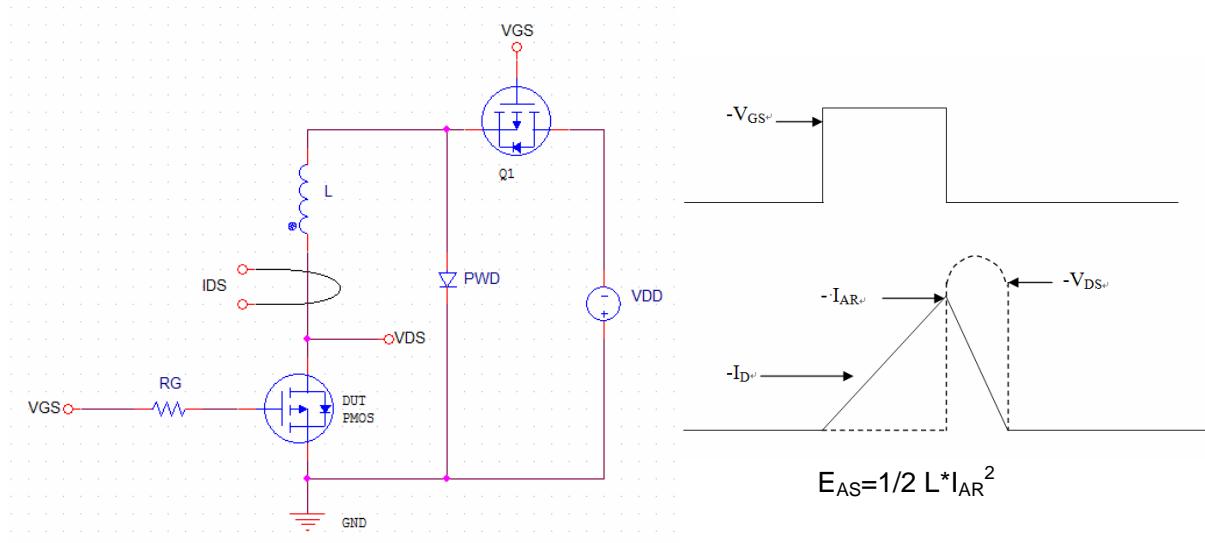
Drain Current VS Gate-Source Voltage



On-Resistance vs. Junction

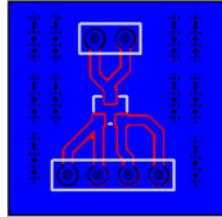

Gate-Charge Characteristics

Capacitance Characteristics

Maximum Forward Biased Safe Operating Area (Note E)

Single Pulse Power Rating Junction-to-Ambient (Note E)

Normalized Maximum Transient Thermal Impedance

Avalanche Energy(Single pulsed) Test Circuit & Waveforms



Power Dissipation Characteristics

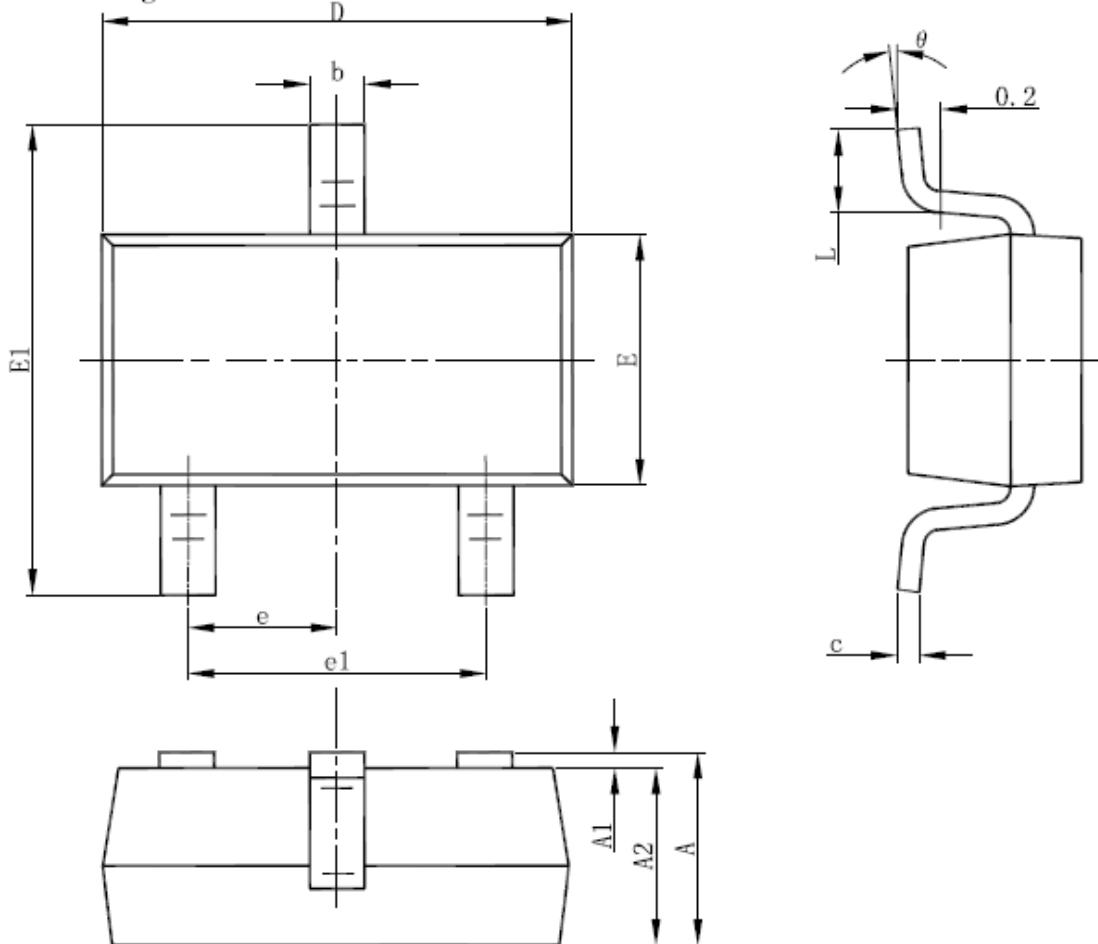
1. The package of WPM3407 is SOT23-3, surface mounted on FR4 Board using 1 in sq pad size, 1 oz Cu, $R_{\theta JA}$ is 125 °C/W.
2. The power dissipation P_D is based on $T_{J(MAX)}=150^\circ\text{C}$, and the relation between T_J and P_D is $T_J = T_a + R_{\theta JA} * P_D$, the maximum power dissipation is determined by $R_{\theta JA}$.
3. The $R_{\theta JA}$ is the thermal impedance from junction to ambient, using larger PCB pad size can get smaller $R_{\theta JA}$ and result in larger maximum power dissipation.



125 °C/W when mounted on
a 1 in² pad of 1 oz copper.

Packaging Information

SOT-23-3 Package Outline Dimension



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

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